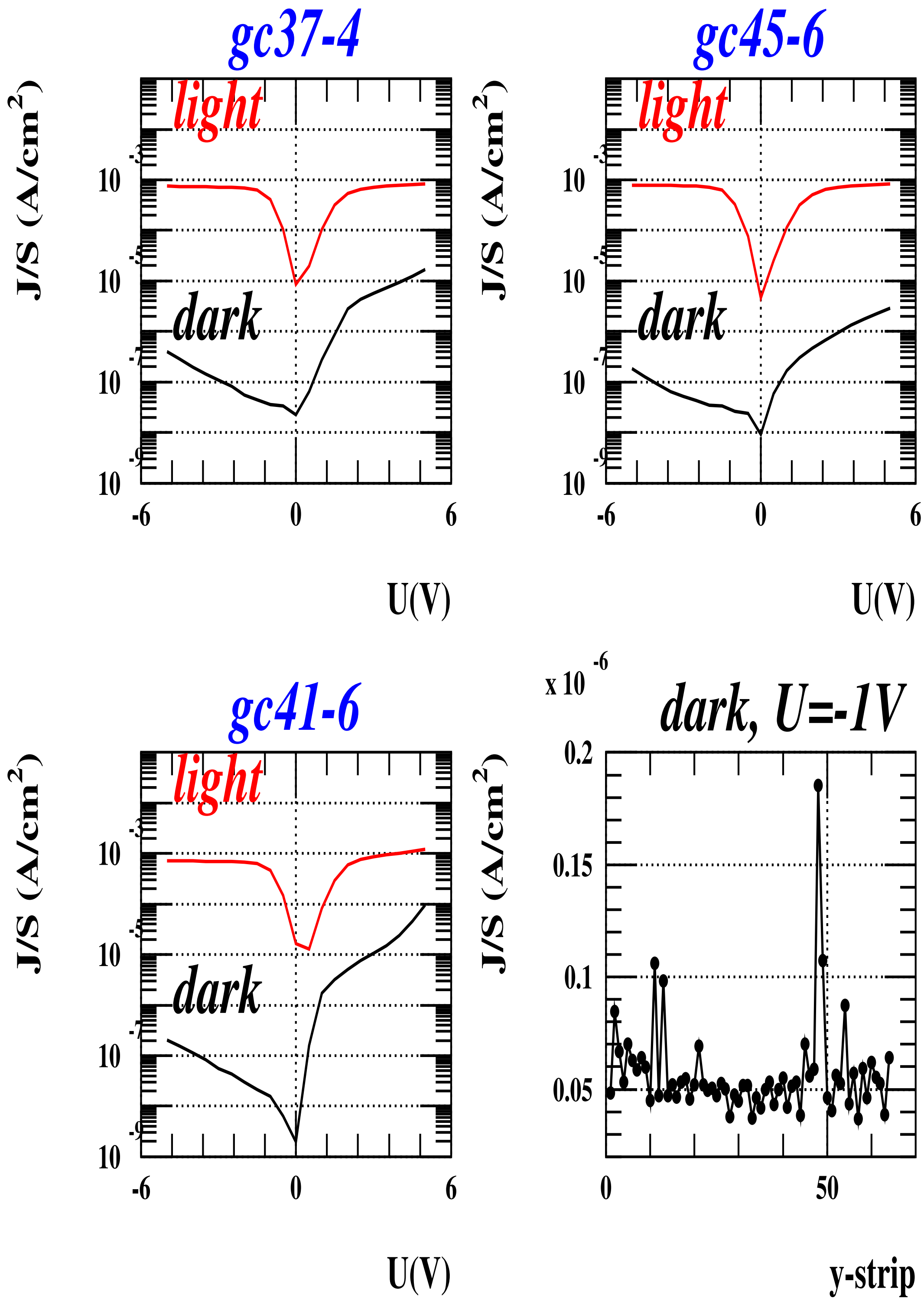
gc37-4
gc45-6
gc41-6
dark, U=-1V
light
dark
J/S (A/cm^2)
U(V)
y-strip
x 10^{-6}

HLL SUMMARY:

sensor wafer →	gc37	gc41	gc45
cell 1	bad: 2x, 10y	bad: 3x, 2y	bad: 20y
cell 2	bad: 10x dead: 10y	bad: many	bad: many
cell 3	bad: 10x, 2y dead: 3x	bad: 1x, 1y	bad: 10x, 5y
cell 4	bad: 4x, 4y	bad: 32x, 15y	bad: 5x, 6y
cell 5	dead: 1x	bad: 7x, 3y 5 bonds scratched	bad: 20y
cell 6	bad: 2x, 2y	bad: 2y dead: 15x	bad: 1x, 4y

Classification:
2. class
3. class
4. class
5. class

- **A lot of impurities on the silicon layer, for all wafers**
- **Bond-pads seem to be OK**

- only for one sensor 5 connections are broken, the scratch is visible

- ***The biggest problem*** **-** inhomogeneity of the silicon layer -> bad diodes